

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 292873US41PCT		SERIAL NO. 10/584,052	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Stephane POCAS, et al.			
				FILING DATE June 22, 2006		GROUP 2892	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	6,340,812	01/22/02	Yoshihiro IZUMI, et al			
	AB	2004/0097008 A1	05/2004	Glen J. LEEDY			
	AC	5,374,564	12/20/94	Michael BRUEL			
	AD	6,281,039	08/28/01	MARION			
	AE	2004/0014299	01/22/04	Hubert MORICEAU, et al.			
	AF	5,880,010	03/1999	Davison, HOWARD L.			
	AG	6,097,096	08/2000	GARDNER, et al.			
	AH	6,465,892	10/2002	SUGA, Tadatomo			
	AI	6,809,008	10/2004	HOLM, et al.			
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	AK	6,902,987	06/2005	TONG, et al.			
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	AN	2002/0173118	11/2002	DIETRICH, et al.			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
	AO	2 783 969	03/31/00	France (equivalent of US 6, 281, 039)			X
	AP	2 816 445	05/10/02	France (equivalent of US 2004/0014299)			X
	AQ	WO/2003/028101	04/2003	France (equivalent of US 2005/0020029)			X
	AR	WO/01/18853 A1	03/2001	World Intellect (equivalent of US 7,208,392)			X
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW	Q.-Y. TONG, et al., "SEMICONDUCTOR WAFER BONDING: SCIENCE AND TECHNOLOGY", JOHN WILEY & SONS, INC., XP 008042464, pages 215-219, 1999.					
	AX	Goran THUNGSTROM, et al., "CONTACTS TO MONOCRYSTALLINE N - AND P- TYPE CILLICON BY WAFER BONDING USING COBALT DISILICIDE", Physica Scripta, Vol. T54, 1994, pages 77-80.					
	AY	ISMAIL, M.S., et al., "PLATINUM SILICIDE FUSION BONDING", Electronics Letters, Vo. 27, No. 13, pages 1153-1155, 1991.					
	AZ	PLOESSL, A., et al., "WAFER DIRECT BONDING: TAILORING ADHESION BETWEEN BRITTLE MATERIALS", Materials Science and Engineering, Vol. 25, No. 1-2, pages 1-88, 1999.				<input checked="" type="checkbox"/> Additional References sheet(s) attached	
Examiner					Date Considered		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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	BA	2003/0129780	07/2003	Andre AUBERTON-HERVE			
	BB	2005/0020029	01/2005	JEAN-SEBASTIEN, Danel			
	BC	2005/0104089	05/2005	ENGELMANN, et al.			
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	BG	2008/0296712	12/04/08	Guy FEUILLET, et al.			
	BH						
	BI						
	BJ						
	BK						
	BL						
	BM						
	BN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
	BO						
	BP						
	BQ						
	BR						
	BS						
	BT						
	BU						
	BV						
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	BW	SHIGETOU, A., et al., "ROOM TEMPERATURE BONDING OF ULTRA-FINE PITCH AND LOW-PROFILED CU ELECTRODES FOR BUMP-LESS INTERCONNECT", Electronic Components and Technology Conference, Vol. 53, pages 848-852, 2003.					
	BX	LJUNGBERG, K., et al., "BURIED COBALT SILICIDE LAYERS IN SILICON CREATED BY WAFER BONDING", Journal of the Electrochemical Society, Vol. 141, No. 10, pages 2829-2833, 1994.					
	BY	B. ASPAR, et al., "SMART-CUT PROCESS USING METALLIC BONDING: APPLICATION TO TRANSFER OF Si, GaAs, InP THIN FILMS", Electronics Letters, Vol. 35, No. 12, June 10, 1999, pages 1024-1025.					
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